



PARA LIGHT ELECTRONICS CO., LTD.

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DATA SHEET

PART NO.: L-C192JYCT

REV: A/0

CUSTOMER'S APPROVAL : _____

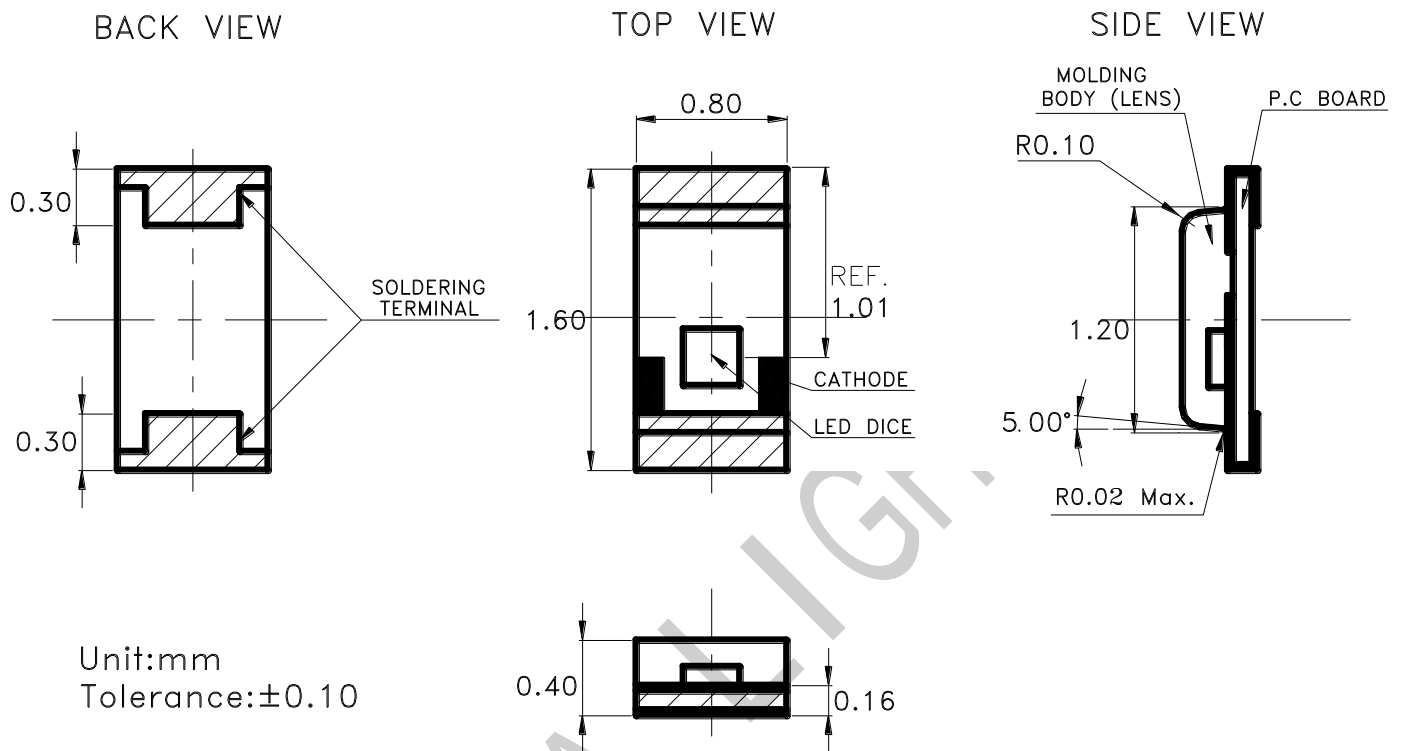
DCC : _____

DRAWING NO. : DS-75-21-0002G

DATE : 2021-01-15

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● PACKAGE OUTLINE DIMENSIONS



Notes:

1. All dimensions are in millimeters.
2. Tolerance is $\pm 0.1\text{mm}$ (.004") unless otherwise noted.

● Features

- * Top view, wide view angle, single color Chip LED.
- * Package in 8mm tape on 7" diameter reels.
- * Compatible with automatic Pick & Place equipment.
- * Compatible with Infrared and Wave soldering reflow solder processes.
- * EIA STD package.
- * I.C. compatible.
- * Pb free product.
- * Meet RoHS Green Product.
- * Moisture sensitivity level: 3

● **CHIP MATERIALS**

- * Dice Material : AlInGaP
- * Light Color : Yellow
- * Lens Color : Water Clear

● **Absolute Maximum Ratings(Ta=25°C)**

| Symbol | Parameter | Rating | Unit |
|--------|--|-----------|------|
| PD | Power Dissipation | 75 | mW |
| IPF | Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width) | 80 | mA |
| IF | Continuous Forward Current | 30 | mA |
| VR | Reverse Voltage | 5 | V |
| Topr | Operating Temperature Range | -40 ~ +85 | °C |
| Tstg | Storage Temperature Range | -40 ~ +85 | °C |

● **Electro-Optical Characteristics(Ta=25°C)**

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test Condition |
|--------------------------|--------|------|------|------|------|-------------------|
| Luminous Intensity | IV | 40 | 80 | | mcd | IF=20mA |
| Viewing Angle | 2θ 1/2 | | 130 | | deg | Note 2 |
| Peak Emission Wavelength | λ p | | 592 | | nm | Measurement @Peak |
| Dominant Wavelength | λ d | | 590 | | nm | IF=20mA |
| Spectral Line Half-Width | Δ λ | | 20 | | nm | |
| Forward Voltage | VF | | 2.05 | 2.4 | V | IF =20mA |
| Reverse Current | IR | | | 10 | μ A | VR = 5V |

● Bin Code List

| Luminous Intensity(IV), Unit:mcd@20mA | | |
|---------------------------------------|-----|-----|
| Bin Code | Min | Max |
| R1 | 40 | 60 |
| R2 | 60 | 90 |
| S1 | 90 | 130 |
| S2 | 130 | 180 |
| | | |

Tolerance of each bin are $\pm 15\%$

| Forward Voltage(VF), Unit:V@20mA | | |
|----------------------------------|-----|-----|
| Bin Code | Min | Max |
| 4 | 1.9 | 2.0 |
| 5 | 2.0 | 2.1 |
| 6 | 2.1 | 2.2 |
| 7 | 2.2 | 2.3 |
| 8 | 2.3 | 2.4 |

Tolerance of each bin are ± 0.1 Volt

| Dominant Wavelength (Hue),Unit: nm@20mA | | |
|---|-------|-------|
| Bin Code | Min | Max |
| YA01 | 587.0 | 589.0 |
| YA02 | 589.0 | 591.0 |
| YB01 | 591.0 | 593.0 |
| YB02 | 593.0 | 595.0 |
| YC01 | 595.0 | 597.0 |

Tolerance of each bin are ± 0.5 nm

Notes:

1. Luminous intensity is measured with a light sensor and filter combination that proximates the CIE eye-response curve.
2. θ 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
3. Caution in ESD :
Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

● Typical Electro-Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

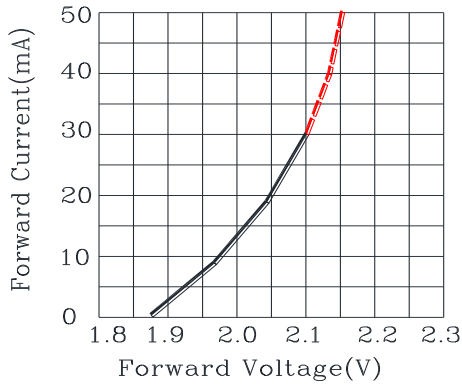


Fig.2 Forward Current vs. Forward Voltage

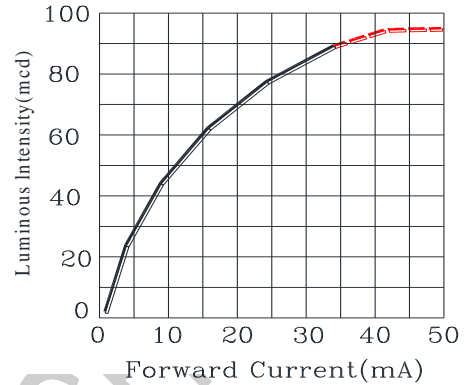


Fig.3 Luminous Intensity vs. Forward Current

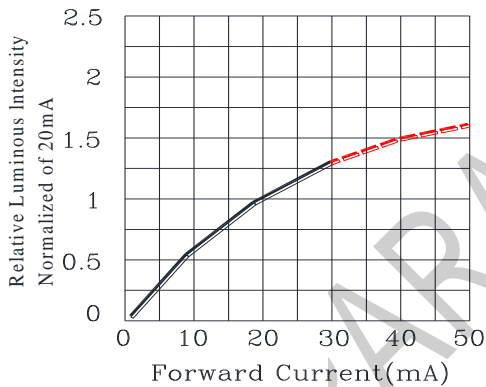


Fig.4 Relative Luminous Intensity vs. Forward Current

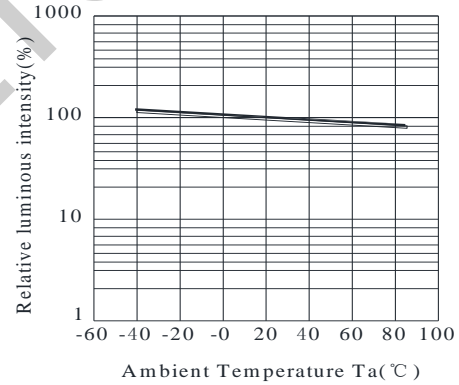


Fig.5 Luminous Intensity vs. Ambient Temperature

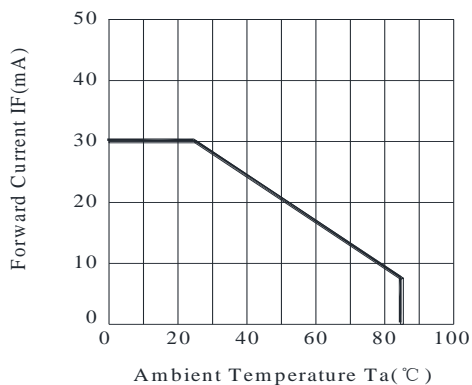


Fig.6 Forward Current Derating Curve

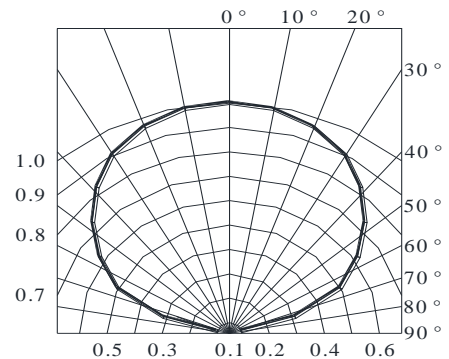


Fig.7 Relative Intensity vs. Angle



SURFACE MOUNT DEVICE LED

Part No. : L-C192JYCT

REV: A/0

● Label Explanation



ITEM CODE:PARRA LIGHT

PART NO: L-C192JYCT

IV --- Luminous Intensity Code

| | | | | | | |
|---------|-----------|----------|----------|-----------|-----------|-------------|
| LOT NO: | <u>EM</u> | <u>S</u> | <u>L</u> | <u>12</u> | <u>09</u> | <u>0110</u> |
| | A | B | C | D | E | F |

A---EM: Emos Code

B---S:SMD

L---Local

D---Year

E---Month

F---SPEC.

PACKING QUANTITY OF BAG :

3000pcs for 150、170、110、155、115 series

4000pcs for 191 series

5000pcs for 192 series

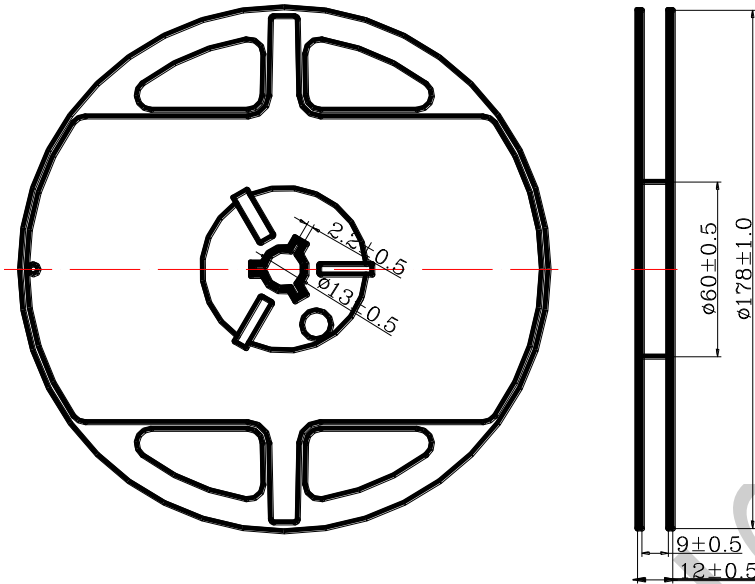
| | | | |
|------------|-------------|-----------|-----------|
| DATE CODE: | <u>2012</u> | <u>09</u> | <u>10</u> |
| | G | H | I |

G--- Year

H--- Month

I --- Day

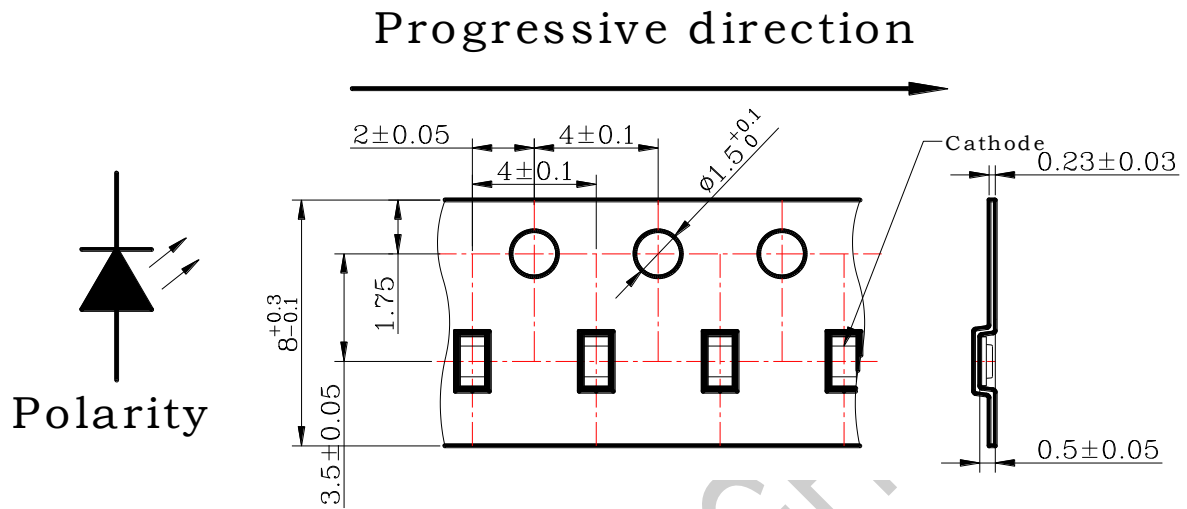
● Reel Dimensions



Notes:

1. Taping Quantity : 5000pcs
2. The tolerances unless mentioned is ± 0.1 mm, Angle $\pm 0.5^\circ$, Unit : mm.

● Package Dimensions Of Tape And Reel

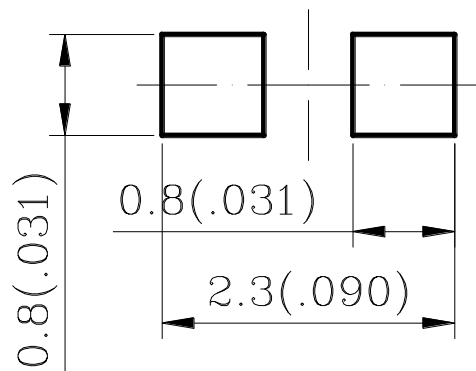


Notes: All dimensions are in millimeters.

● Cleaning

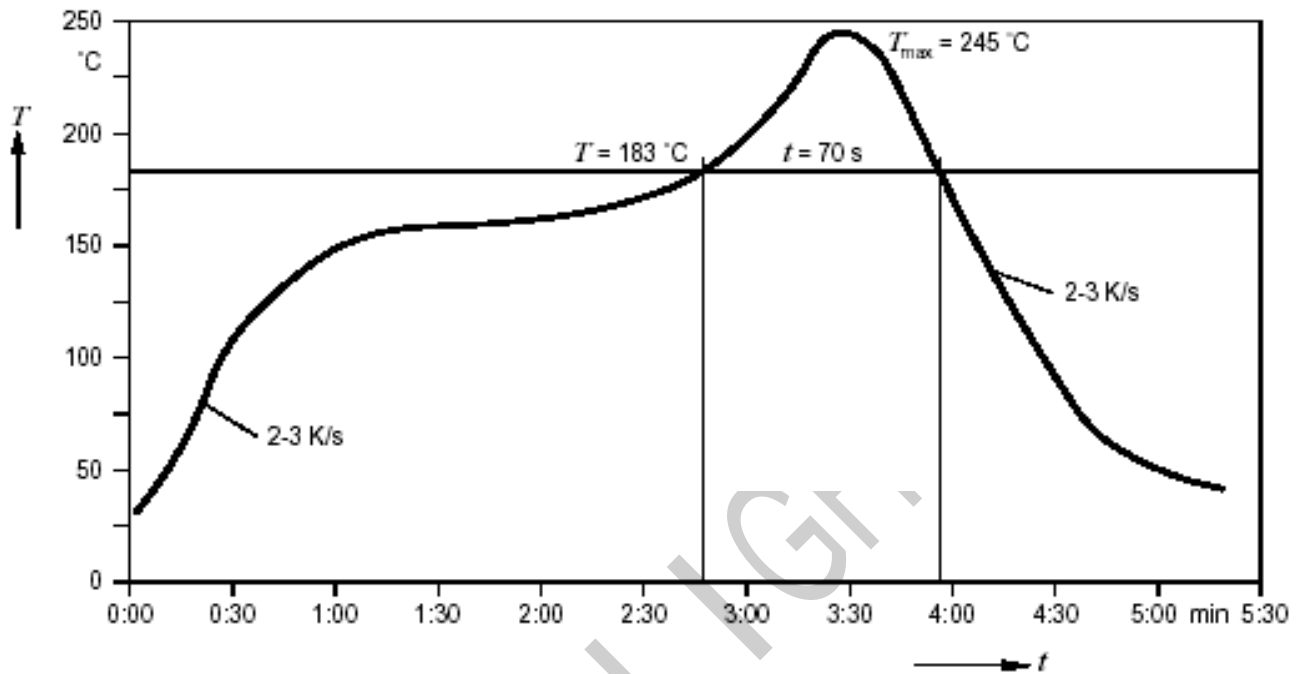
- * If cleaning is required , use the following solutions for less than 1 minute and less than 40°C.
- * Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- * Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

● Suggest Soldering Pad Dimensions

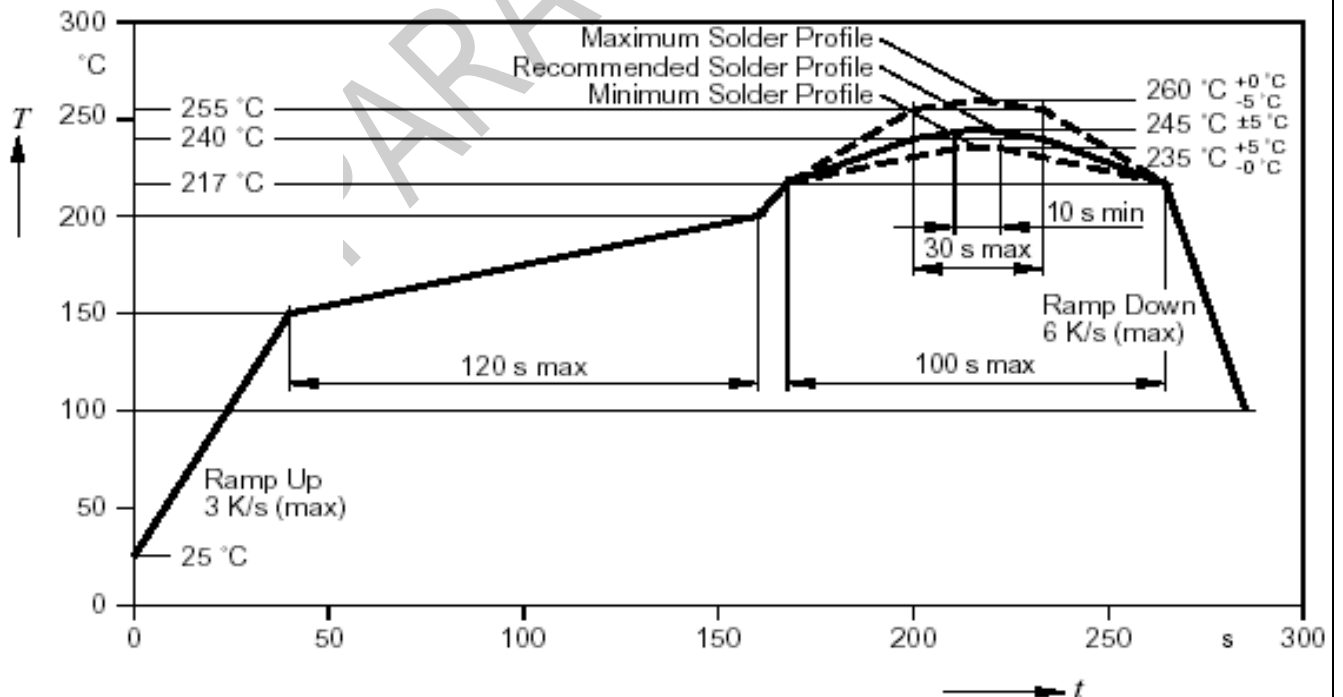


Direction of PWB camber
and go to reflow furnace

● Suggest Sn/Pb IR Reflow Soldering Profile Condition:



● Suggest Pb-Free IR Reflow Soldering Profile Condition:



● CAUTIONS

1.Application Limitation :

The LED's described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household application). Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

2.Storage :

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: $60 \pm 5^{\circ}\text{C}$ for 24 hours.

3.Soldering

Do not apply any stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering condition.

Reflow Soldering :

Pre-heat $120 \sim 150^{\circ}\text{C}$, 120sec. MAX., Peak temperature : 240°C Max. Soldering time : 10 sec Max.

Soldering Iron : (Not recommended)

Temperature 300°C Max., Soldering time : 3 sec. Max.(one time only), power dissipation of iron : 20W Max. use SN60 solder of solder with silver content and don't to touch LED lens when soldering.

Wave soldering :

Pre-heat 100°C Max, Pre-heat time 60 sec. Max, Solder wave 260°C Max, Soldering time 5 sec. Max. performed consecutively cooling process is required between 1st and 2nd soldering processes.

4. Lead-Free Soldering

For Reflow Soldering :

- 1、Pre-Heat Temp: 150-180°C,120sec.Max.
- 2、Soldering Temp: Temperature Of Soldering Pot Over 230°C,40sec.Max.
- 3、Peak Temperature: 260°C、5sec.
- 4、Reflow Repetition: 2 Times Max.
- 5、Suggest Solder Paste Formula : 93.3 Sn/3.1 Ag/3.1 Bi/0.5 Cu

For Soldering Iron (Not Recommended) :

- 1、Iron Tip Temp: 350°C Max.
- 2、Soldering Iron: 30w Max.
- 3、Soldering Time: 3 Sec. Max. One Time.

For Dip Soldering :

- 1、Pre-Heat Temp: 150°C Max. 120 Sec. Max.
- 2、Bath Temp: 265°C Max.
- 3、Dip Time: 5 Sec. Max.

5. Drive Method



(A)Recommended circuit.

(B)The difference of brightness between LED`s could be found due to the Vf-If characteristics of LED.